

# 1.5V Drive Pch MOSFET

## RT1A040ZP

### ●Structure

Silicon P-channel MOSFET

### ●Features

- 1) Low on-resistance.
- 2) High power package.
- 3) Low voltage drive. (1.5V)

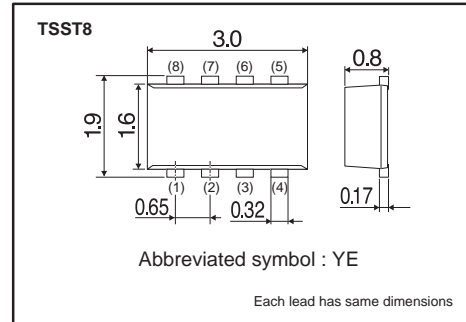
### ●Applications

Switching

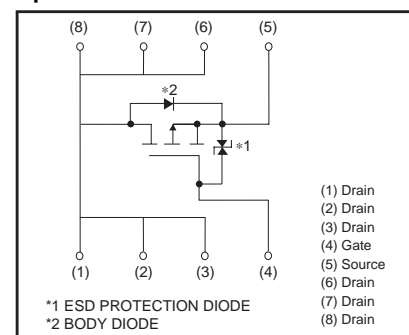
### ●Packaging specifications

Type	Package	Taping
	Code	TR
	Basic ordering unit(pieces)	3000
RT1A040ZP		○

### ●Dimensions (Unit : mm)



### ●Equivalent circuit



### ●Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit
Drain-source voltage	$V_{DS}$	-12	V
Gate-source voltage	$V_{GS}$	±10	V
Drain current	Continuous	$I_D$	A
	Pulsed	$I_{DP}$ *1	A
Source current (Body diode)	Continuous	$I_S$	A
	Pulsed	$I_{SP}$ *1	A
Total power dissipation	$P_D$	1.25	W *2
Channel temperature	$T_{ch}$	150	°C
Range of Storage temperature	$T_{stg}$	-55 to +150	°C

\*1  $P_w \leq 10\mu s$ , Duty cycle  $\leq 1\%$

\*2 When mounted on a ceramic board

### ●Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	$R_{th(ch-a)}$ *	100	°C / W

\* When mounted on a ceramic board

## ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	—	—	±10	μA	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR) DSS</sub>	-12	—	—	V	I <sub>D</sub> = -1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	—	—	-1	μA	V <sub>DS</sub> = -12V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS(th)</sub>	-0.3	—	-1.0	V	V <sub>DS</sub> = -6V, I <sub>D</sub> = -1mA
Static drain-source on-state resistance	R <sub>DS(on)</sub> *	—	22	30	mΩ	I <sub>D</sub> = -4A, V <sub>GS</sub> = -4.5V
		—	30	42	mΩ	I <sub>D</sub> = -2A, V <sub>GS</sub> = -2.5V
		—	40	60	mΩ	I <sub>D</sub> = -2A, V <sub>GS</sub> = -1.8V
		—	55	110	mΩ	I <sub>D</sub> = -0.8A, V <sub>GS</sub> = -1.5V
Forward transfer admittance	Y <sub>fs</sub>   *	6.5	—	—	S	V <sub>DS</sub> = -6V, I <sub>D</sub> = -4A
Input capacitance	C <sub>iss</sub>	—	2350	—	pF	V <sub>DS</sub> = -6V
Output capacitance	C <sub>oss</sub>	—	310	—	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	C <sub>rss</sub>	—	280	—	pF	f=1MHz
Turn-on delay time	t <sub>d(on)</sub> *	—	11	—	ns	V <sub>DD</sub> ≐ -6V
Rise time	t <sub>r</sub> *	—	70	—	ns	I <sub>D</sub> = -2A
Turn-off delay time	t <sub>d(off)</sub> *	—	380	—	ns	V <sub>GS</sub> = -4.5V
Fall time	t <sub>f</sub> *	—	210	—	ns	R <sub>L</sub> ≐ 3Ω
Total gate charge	Q <sub>g</sub> *	—	30	—	nC	V <sub>DD</sub> ≐ -6V R <sub>L</sub> ≐ 1.5Ω
Gate-source charge	Q <sub>gs</sub> *	—	4.0	—	nC	I <sub>D</sub> = -4A R <sub>G</sub> =10Ω
Gate-drain charge	Q <sub>gd</sub> *	—	3.5	—	nC	V <sub>GS</sub> = -4.5V

\*Pulsed

## ●Body diode characteristics (Source -drain) (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V <sub>SD</sub> *	—	—	-1.2	V	I <sub>S</sub> = -4A, V <sub>GS</sub> =0V

\*Pulsed

## ●Electrical characteristic curves

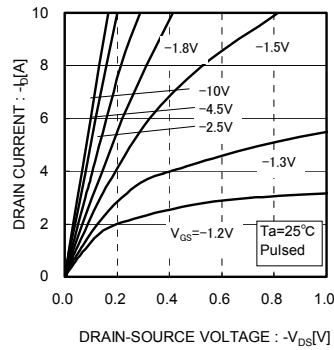


Fig.1 Typical Output Characteristics( I )

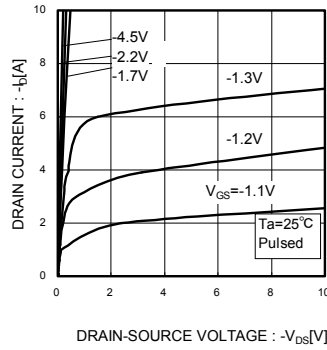


Fig.2 Typical Output Characteristics( II )

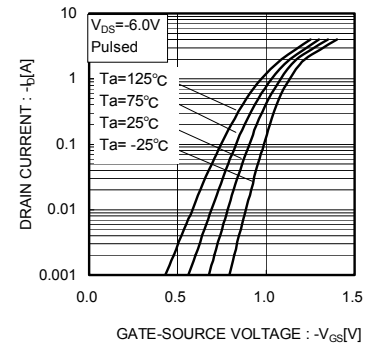


Fig.3 Typical Transfer Characteristics

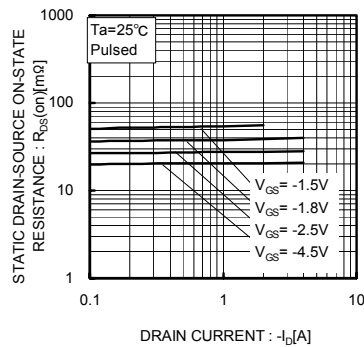


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

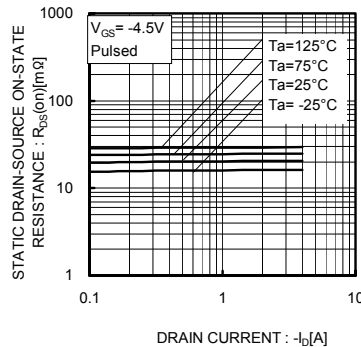


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current( II )

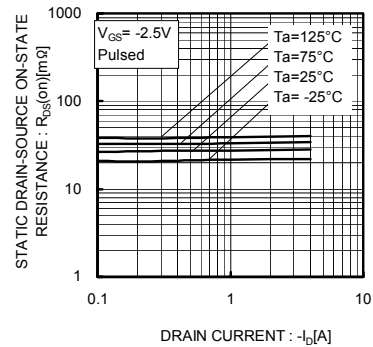


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current(III)

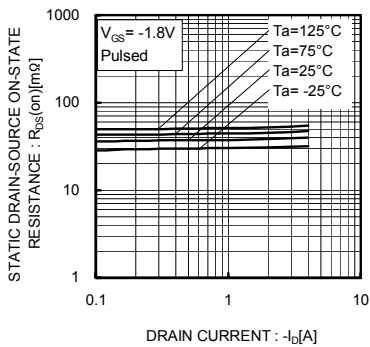


Fig.7 Static Drain-Source On-State Resistance vs. Drain

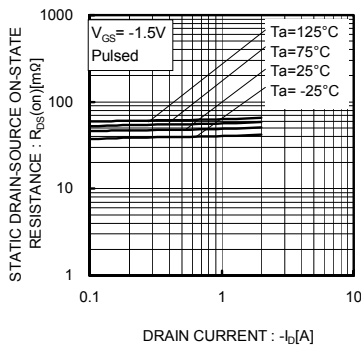


Fig.8 Static Drain-Source On-State Resistance vs. Drain

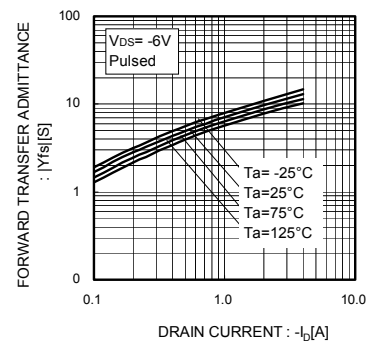


Fig.9 Forward Transfer Admittance vs. Drain Current

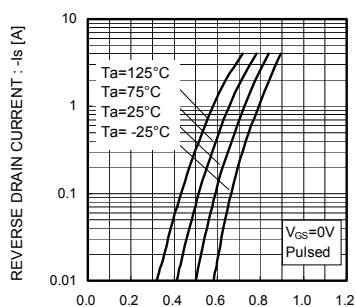
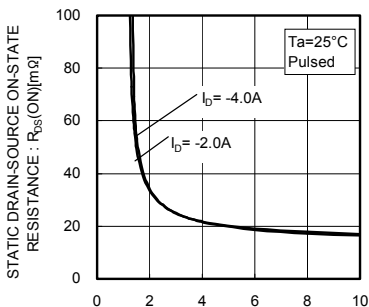
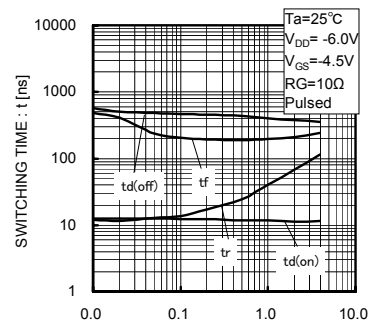
SOURCE-DRAIN VOLTAGE :  $-V_{SD}$  [V]Fig.10 Reverse Drain Current  
vs. Source-DrainGATE-SOURCE VOLTAGE :  $-V_{GS}$  [V]Fig.11 Static Drain-Source On-State  
Resistance vs. Gate SourceDRAIN-CURRENT :  $-I_D$  [A]

Fig.12 Switching Characteristics

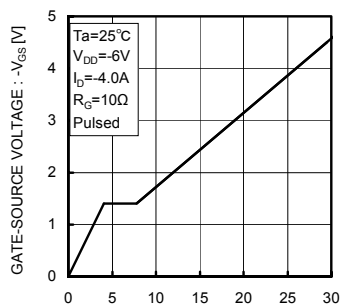
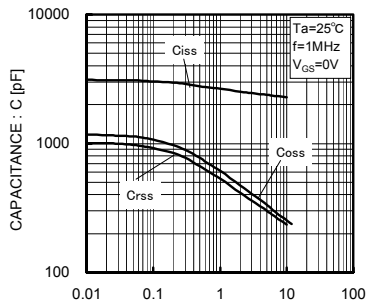
TOTAL GATE CHARGE :  $Q_g$  [nC]

Fig.13 Dynamic Input Characteristics

DRAIN-SOURCE VOLTAGE :  $-V_{DS}$  [V]Fig.14 Typical Capacitance  
vs. Drain-Source

### ●Measurement circuits

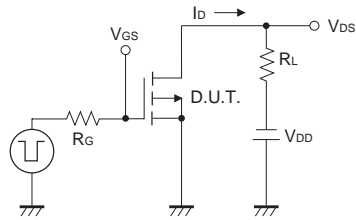


Fig.1-1 Switching Time Measurement Circuit

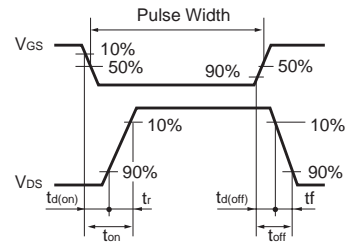


Fig.1-2 Switching Waveforms

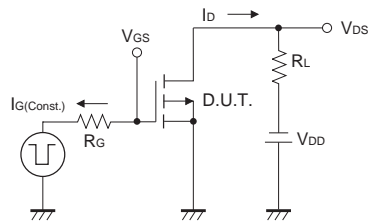


Fig.2-1 Gate Charge Measurement Circuit

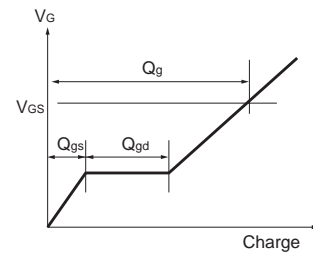


Fig.2-2 Gate Charge Waveform

### ●Notice

This product might cause chip aging and breakdown under the large electrified environment.  
Please consider to design ESD protection circuit.

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